

VERSION WITH MARKINGS TO SHOW CHANGES MADE

29. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor;
and

an attachment device arranged to press said semiconductor against said interconnect structure ~~pressing said interconnect structure against said semiconductor~~ to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including an elastomeric ~~member~~ elastic member comprised of a first elastomeric material, and a conductive member.

44. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor;
and

an attachment device ~~pressing said~~ arranged to press semiconductor ~~interconnect structure against said semiconductor~~ interconnect structure to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including a conductive member and a first elastic member comprised of a first elastomeric material having ~~a first modulus of elasticity~~ first force transfer characteristics, said first elastic member having a plurality of holes formed therein such that said spring element has ~~an overall modulus of elasticity~~ force transfer characteristics different from said first ~~modulus of elasticity~~ force transfer characteristics.

45. (Amended) The apparatus of claim 44, wherein said spring element further comprises an elastic member comprised of a second elastomeric material having ~~a second modulus of elasticity~~ second force transfer characteristics, said second elastic member positioned in at least one of said plurality of holes formed in said first elastic member such that said overall ~~modulus of elasticity~~ force transfer characteristics ~~are~~ is different from said first and second ~~moduli of elasticity~~ force transfer characteristics.

50. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor;
and

an attachment device arranged to press said semiconductor against said interconnect structure ~~pressing said interconnect structure against said semiconductor~~ to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including an elastic member comprised of a conductive member and an elastomeric material having first force transfer characteristics, said first elastic member having at least one hole formed therein such that said spring element has overall force transfer characteristics different from said first force transfer characteristics ~~a modulus of elasticity~~, ~~said elastic member having a hole formed therein such that said spring element has an overall modulus of elasticity different from said modulus of elasticity of said elastomeric material~~, said elastic member being shaped so as to engage an outer edge of said semiconductor such that a force applied by said attachment device as said ~~interconnect structure~~ semiconductor is pressed by said attachment device ~~against said semiconductor~~ against said semiconductor-interconnect structure is substantially uniform around said semiconductor.

54. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor;
and

an attachment device pressing said interconnect structure against said semiconductor to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including a first conductive member, a first elastic member and a second elastic member, said first elastic member comprising a first elastomeric material having a first modulus of elasticity~~first force transfer characteristics~~ and said second elastic member comprising a second elastomeric material having a ~~second modulus of elasticity~~second force transfer characteristics, said second elastic member being positioned within said first elastic member such that said spring element has an overall ~~modulus of elasticity~~force transfer characteristics different from said first and second ~~moduli of elasticity~~force transfer characteristics.

63. (Amended) An apparatus for attaching to a plurality of contacts of a semiconductor, said apparatus comprising:

an interconnect structure comprising a plurality of conductors patterned to match corresponding ones of said plurality of contacts of said semiconductor;
and

an attachment device ~~pressing said interconnect structure~~arranged to press said semiconductor against said ~~semiconductor interconnect structure~~ to provide an electrical connection between said plurality of conductors and said corresponding ones of said plurality of contacts, said attachment device comprising a spring element including a conductive member and an elastic member comprised of an elastomeric material having a ~~modulus of elasticity~~first force transfer characteristics, said elastic member having at least one cavity

formed therein such that said spring element has an overall modulus of elasticity
force transfer characteristics different from said ~~modulus of elasticity~~ first transfer
characteristics of said elastomeric material.